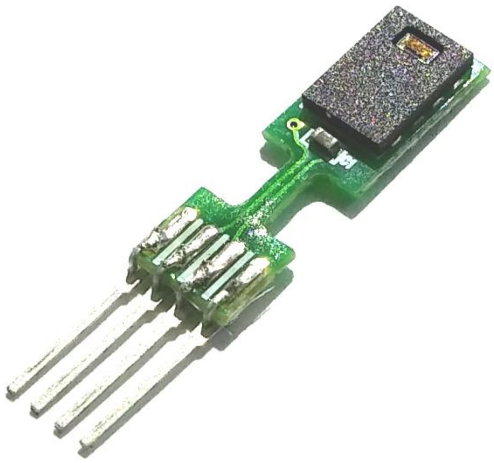
HCS2D-3V

Humidity & Temperature Solution

Enhanced Features

- **Fully Calibrated & Temperature Compensated**
- **Improved Temperature Accuracy & Range (±0.2℃ for -20 ~ 60℃)**
- **Extremely Low Current Consumption (13uA operating)**
- **Enhanced Accuracy of RH% (±2%RH, 14bit)**
- **Fast Natural Recovery after Reflow Soldering**
- **Low Current Consumption**
- **SIP(Single-In-line-Package)**
- **Enhanced Reliability against Chemical**



Product Summary

HCS2D-3V is a Single In-Line Package type of **HumiChipII®** with ready installed V-Core capacitor for easy and convenient application.

HumiChipII® is an improved version of **HumiChip®**, the most advanced and cost effective humidity and temperature sensing solution for virtually any type of applications.

Capacitive polymer sensor chip developed and fabricated in-house and CMOS integrated circuit with EEPROM are integrated into one embedded system in a reflow solder-able SMD package.

Individually calibrated and tested, **HumiChipII®** performs ±2% from 20% to 80%RH (±4% over entire humidity range), and yet, is simple and ready to use without further calibration or temperature compensation.

Designed and manufactured by industry leading humidity and temperature sensing technology of **SAMYOUNG S&C** – field proven in HVAC and Auto industry for over 15 years, **HumiChipII®** offers another smart sensing solution for excellent reliability, high accuracy, and cost effective sensing applications.

Application

Energy Saving HVAC Control

Air Conditioning, Refrigeration, IAQ monitoring, Vent Fans, Home Appliances, Humi/Dehumidifiers

Automobile & Transportation

Cabin Climate Control, Defogging Control Condensing Preventive Device …,

Process Control & Instrumentations

Medical Instruments, Handheld Devices, Weather Stations, Food Processing, Printers, RFIDs …

Mass Quantity Application

OEM custom specification available

技术 & 商务联系方式: 南频科技有限公司
陈小姐 业务工程师 156 2521 4151
rita.chen@dwintech.com www.dwintech.com
座机0755-82565851

Sensor Performance

Relative Humidity (RH%)

Resolution	**14 bit** (0.01%RH)
Accuracy[1]	**±2.0** %RH (Figure 1)*
Repeatability	**±0.2** %RH
Hysteresis	**±1.5** %RH
Linearity	**<2.0** %RH
Response time[2]	**Max 8.0** sec (τ 63%)
Temp Coefficient	**0.05** %RH/℃ (at 10 ~ 60℃, 10 ~ 90%RH)
Operating range	**0 ~ 100** %RH (Non-Condensing)
Long term drift	**<0.5** %RH/yr (Normal condition)

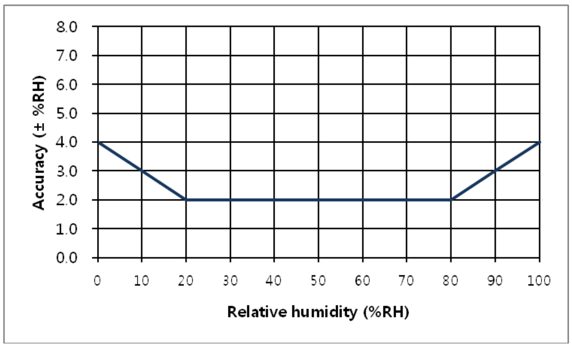
** Custom Accuracy Tolerance Available*

Temperature (°C)

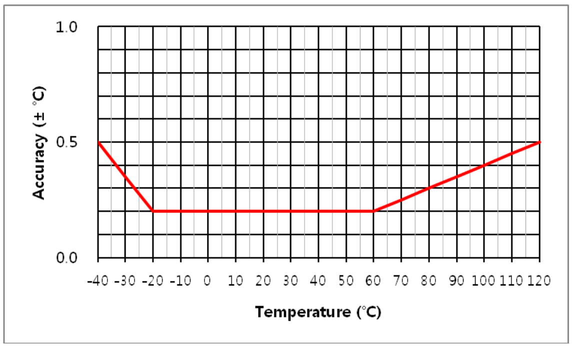
Resolution	**14 bit** (0.01℃)
Accuracy[3]	**±0.2** ℃ **(Figure 2)**
Repeatability	**±0.1** ℃
Response time[4]	**10.0** sec (τ 63%)
Operating range	**- 40 ~ 125** ℃
Long term drift	**<0.05** ℃/yr (Normal condition)

1. *Accuracies measured at 25 ℃, 3.3V.*
2. *Measured at 25 ℃, 1m/sec airflow for achieving 63% of step from 10%RH to 90%RH*
3. *Accuracies measured at 25 ℃, 3.3V.*
4. *Min 5.0 sec, Max 20 sec*

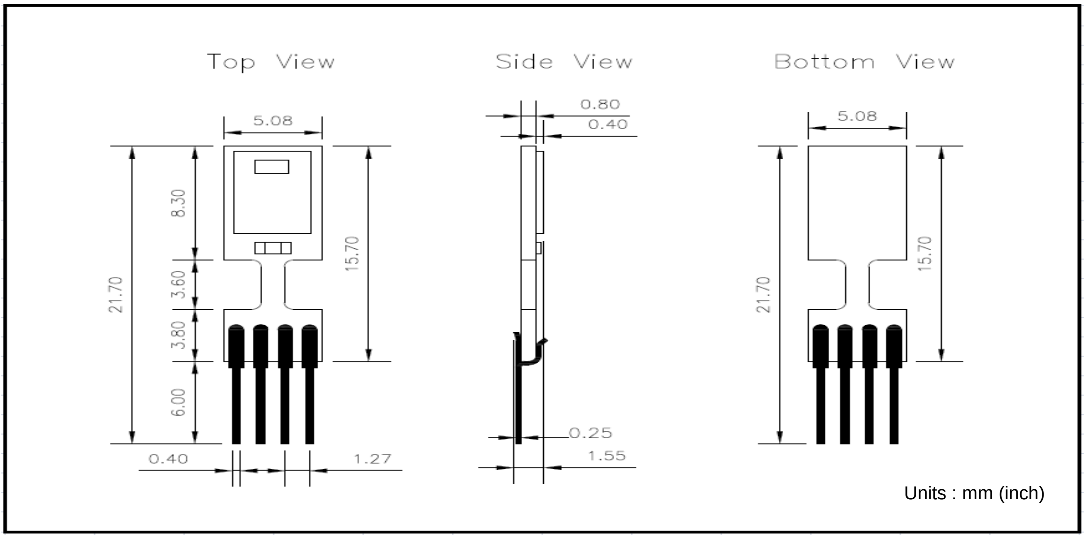
Typical RH% Accuracy at 25℃



Typical Temperature Accuracy



Dimensions



Electrical Specification

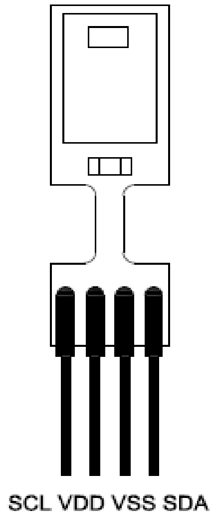
Supply Voltage*1	min 2.1V ~ max 3.3V
Supply Current (IDD)*1	13 ㎂ (typical)

*1. at room temperature

Environmental

Operating Temperature	- 40 ~ 125℃
Operating Humidity	0~100%RH (non condensing)

Pin Connection



*. Chip on Board is 100nF capacitor for Vcore. (Figure. 2.1)

Absolute Maximum Rating

Parameter	Min	Max
Supply Voltage (VDD)	**-0.3V**	**4.0V**
Storage Temp	**-40℃**	**125℃**
Junction Temp	**-40℃**	**125℃**

Soldering Information

Standard or IR Solder Reflow.
IPC/JEDEC standard
T_P ≤250℃, t_P < 10sec, T_L<220℃, t_L<60sec.
Tp(Peak Temperature), t_P(Peak Time),
T_L(Critical Zone Temperature),t_L(Critical Zone Time)
Ramp-up/down speed < 6℃/sec

Package Contents

HCS2D-3V consists of a **HumiChipII®** and a V-core capacitor soldered on the top of a FR4 substrate. Lead Pins are made of Cu, Sn, P alloy and all parts are fully RoHS and REACH compliant.

Shipping

Tray : 100 ea
Inner Box : 500 ea
Out Box : 5,000 ea

Ordering Information

Output		Accuracy	VDD	MODE	Ordering P/N
D	I²C	±2%RH	3.3	Update	**HCS2D-3V**

◆ **For more detail Part Numbers,**
Please refer to the Table 7-1 (P22)

Application Guide

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☞ **Demo Kit** (EVB01-HCP) is available.
A reference program source code can be downloaded from www.samyoungsnc.com

1. General Information

1.1 Preliminary Consideration

To maximize the performance of **HumiChipII®**, it is important to plan an appropriate location of the sensor at the design stage. Airflow and proper exposure to ambient air must be secured for **HumiChipII®** to ensure expected performance. Airflow holes must NOT be blocked. Any heat generating parts near **HumiChipII®** will distort the proper measurement of relative humidity and temperature reading, and either should be avoided or measures should be taken to prevent heat transfer

1.2 Operating Conditions

HumiChipII®'s maximum and recommended normal operating condition is shown in **Figure 1**. Within the Normal Range, **HumiChipII®** performs stably. Prolonged exposures to conditions outside normal range, especially at humidity over 90%RH, may temporarily offset the RH signal up to ±3%RH. When return to Normal Range, it will gradually recover back to the calibration state.

Re-Conditioning Procedure in section 1.6 will help reduce this recovery time. Long term exposure to extreme conditions may also accelerate aging of the sensor.

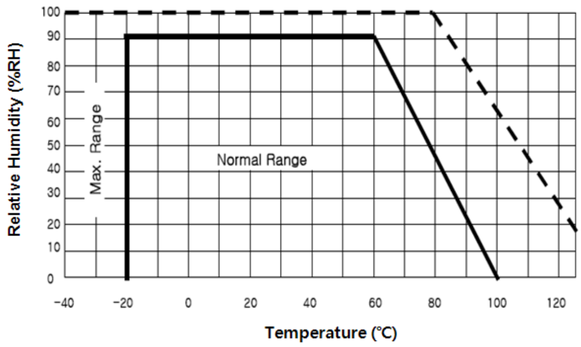


Figure 1 Operating Conditions

1.3 Heating

Heat sources such as power electronics, microcontrollers, and display near the sensor may affect the accurate measurement. The location of Sensor near such heat sources should be avoided by maintaining distance or thermal buffer. Thin metal pattern, or even better, 'milling slits' around the sensor also may help reduce the error.

1.4 Soldering Instruction

HumiChipII® is designed for mass production reflow soldering process. It is qualified for soldering profile according to IPC/JEDEC J-STD-020D (see **Figure 2**) for Pb-free assembly in standard reflow soldering ovens or IR/Convection reflow ovens to withstand peak temperature at 250℃ and peak time up to 10 sec. For soldering in Vapor Phase Reflow (VPR) ovens the peak conditions are limited to T_P < 250℃ with t_P <10sec and ramp-up/down speeds shall be limited to 6℃/sec.

Note : *Test or measurement right after reflow soldering may read an offset as the sensor needs time for stabilization from the soldering heat. The recovery time may vary depending on reflow soldering profile and ambient storage condition.*

For most of the standard reflow soldering, allow 12 hours of stabilization under room environment (23±3℃, 55±5%RH).

NO extra rehydration process is required after reflow soldering for **HumiChipII®**.

Contact our **customer support** for optimal reflow soldering process. [support@samyoungsnc.com]

For **Land Pattern** dimensions,

Note : *The distance between the Vcore capacitor and pad has to be within the 10mm and the tracks of the Power and GND have to be more than 12 mil.*

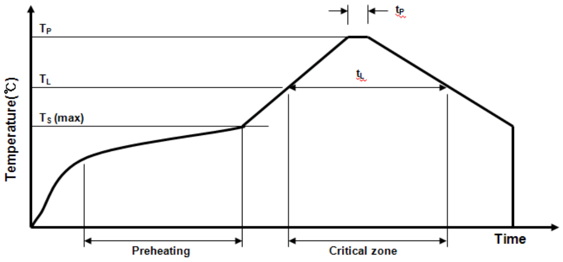


Figure 2 Soldering Profile

IPC/JEDEC standard
$T_P \leq 250$℃, $t_P < 10$sec, $T_L < 220$℃, $t_L < 60$sec.
Ramp-up/down speed < 6℃/sec

1.5 Storage and Handling Information

HumiChipII® contains polymer based capacitive humidity sensor sensitive to environment, and should NOT be handled as an ordinary electronic component.
Chemical vapors at high concentration may interface with the polymer layers, and coupled with long exposure time, may cause a shift in both offset and sensitivity of the sensor.
Despite the sensor endures the extreme conditions of -40℃~125℃, 0%RH~100%RH (non condensing), long term exposure in such environment may also offset the sensor reading. Hence, once the package is opened, it is recommended to store in clean environment of temperature at 5℃~55℃ and humidity at 10%~70%RH.
HumiChipII® is protected of ESD up to 2000V and Latch-up in the range of ±150㎃ to ±200㎃ and also packed in ESD protected shipping material. Normal ESD precaution is required when handling in assembly process.
.

1.6 Reconditioning Procedure

If **HumiChipII®** is exposed or contaminated with chemical vapors, the following reconditioning procedure will recover the sensor back to calibration state.

Baking: **120℃ for 6 hrs** and
Re-Hydration: **30℃ at > 80%RH for 24 hrs**

1.7 Material Contents

HumiChipII® consists of sensor cell and IC (polymer / glass & silicon substrate) packaged in a surface mountable LCC (Leadless Chip Carrier) type package. The sensor housing consists of a PPS (Poly Phenylene Sulfide) cap with epoxy glob top on a standard FR4 substrate. Pads are made of Au plated Cu. The device is free of Pb, Cd and Hg.

<u>RoHS compliant / REACH report available</u>

1.8 Traceability Information

HumiChipII® is laser marked with product type and lot identification.
The first line denotes the sensor type: **HCPA** for **PDM** output, **HCPD** for **I²C** output.
Lot identification is printed on the second line with 5 digit alphanumeric code.
Further information about individual sensor is electronically stored on the chip.

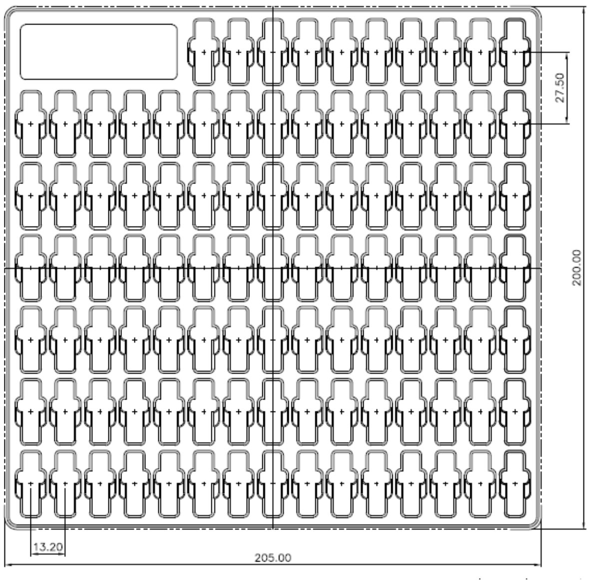
1.9 Shipping Package

HumiChipII® is provided in a tray shipment packaging, sealed into antistatic ESD trays. The drawing of the packaging tapes with sensor orientation and packing box dimensions are shown in Drawing 2

Drawing 1

Packing Tray : 100ea

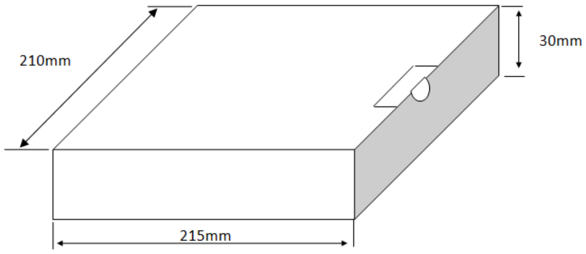
Dimension: 205 x 200 mm



Drawing 2 **Packing (Box)**

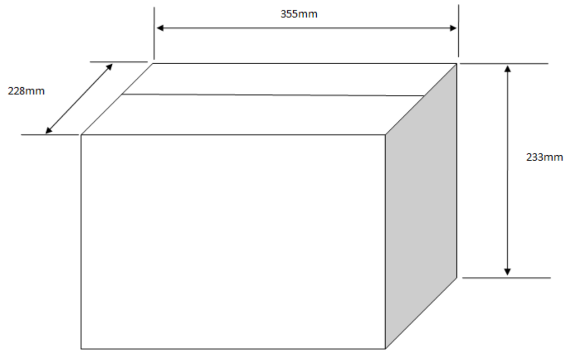
Inbox: 500ea (5+1Tray(For Cover) X 100ea)

Dimension: 215 x 210 x 30 mm



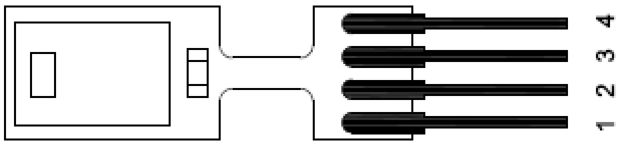
Outbox: 5,000ea (5 x Inbox 500)

Dimension: 355 x 228 x 233 mm



2. Interface Specification

2.1 Digital Output (I²C Interface)



Pin-No	Name	Description
1	SCL	I²C clock
2	VDD	Supply voltage (2.3~5.5V)
3	VSS	Ground
4	SDA	I²C data

2.1.1 Power Pads (2: VDD)

HumiChipII® is capable of operating on wide range of power supply voltage from 2.1V to 3.3V. Recommended supply voltage is either 2.1±0.5V or 3.3±0.5V. Power supply should be connected to VDD (power supply pad 2). VDD and VSS (Ground pad 3) should be decoupled with a *4.7㎌* capacitor.

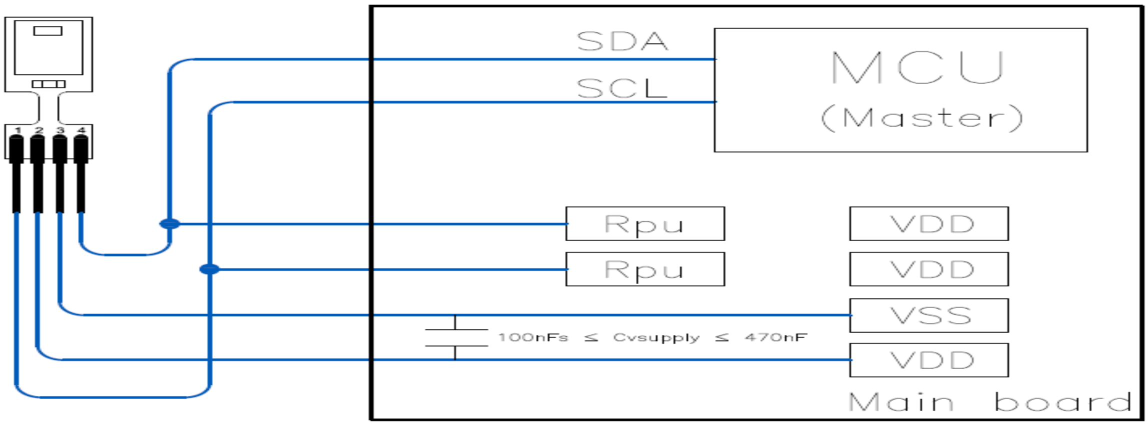
2.1.2 Serial Clock & Data Pads (1: SCL, 4: SDA)

The sensor's data is transferred in and out through the SDA pad while the communication between **HumiChipII®** and microcontroller (MCU) is synchronized through the SCL pad.
HumiChipII® has an internal temperature compensated oscillator that provide time base for all operation, and uses an I²C-compatible communication protocol with support up to 100㎑ bit rates.
External pull-up resistors are required to pull the drive signal high, that can be included in I/O circuits of microcontroller. (see **Figure 3**)
If pads(SDA and SCL) are not used, SCL should be connected to VDD and SDA should be connected GND.

Further information about timing and communication between the sensor and microcontroller is explained in Section 4. Communicating with **HumiChipII®**

Figure 3 Typical Application Circuit (I²C)

- VDD and Ground is decoupled by a (100 ~ 470nF) capacitor.
- Pull-up resistors should be included between **HumiChipII®** and MCU.



3. Electrical Specification

3.1 Absolute Maximum Rating

Table 1 shows the Absolute Maximum Ratings for **HumiChip**II®. Exposure to these extreme conditions for extended period may deteriorate the sensor performance and accelerate aging. Functional operation is not implied at these conditions.

3.2 Electrical Specification and Recommended Operating Conditions

The operating conditions recommended for **HumiChip**II® are given in Table 2 and the electrical specification is shown in Table 3.

3.3 Output Pad Drive Strength

Output pad drive strength is 4mA.

3.4 ESD

All pins have an ESD rating of up to 2kV. The ESD test follows the Human Body Model with C=150pF and R=330Ω based on IEC61000-4-2

Table 1 Absolute Maximum Rating

PARAMETER	SYMBOL	MIN	MAX	Unit
Supply Voltage (VDD to GND)	V_{SUPPLY}	-0.3	4.0	V
Storage Temperature Range	T_{STG}	-40	125	°C
Junction Temperature	T_j	-40	125	°C

Table 2 Recommended Operating Conditions

PARAMETER	SYMBOL	MIN	TYP	MAX	UNIT
Supply Voltage	V_{DD}	2.1		3.6	V
Ambient Temperature Range	T_{AMB}	-40		125	°C
External Capacitance between V_{DD} pin and Gnd	$C_{VSUPPLY}$		10		㎌
External Capacitance between Vcore and Gnd	C_{VCORE}		4.7		㎌
Pull-up on SDA and SCL[*1]	R_{PU}	1			㏀

*1 : The SDA and SCL should not be left in the open state.

*2 : For the capacitor, the X7R or C0G is recommended.

Table 3 Electrical Characteristics Specifications

PARAMETER	SYMBOL	REMARKS	MIN	TYP	MAX	UNIT
Current consumption	I_{DD}	At 3V, 1Hz		13		㎂
Extra Current with PDM enabled[*1]	I_{PDM}				1	㎂
Digital port voltage	$V_{IO\_DIGITAL}$	Relative to ground	-0.6	3.3	V_{DD}+0.6 ≤ 3.6	V
Digital ports switching level		HIGH → LOW LOW → HIGH		0.3*V_{DD} 0.7*V_{DD}		V
Analog port voltage	V_{IO_ANALOG}		-0.6		V_{DD}+0.6 ≤ 3.6	
Start-Up-Time ' Power-on (POR) to data ready	t_{STA}				10	㎳
Measuring Rate				5		㎐
EEPROM Data Retention Period		at 95℃ temperature			10	Year
OTP Data Retention Period		at 95℃ temperature			10	Year

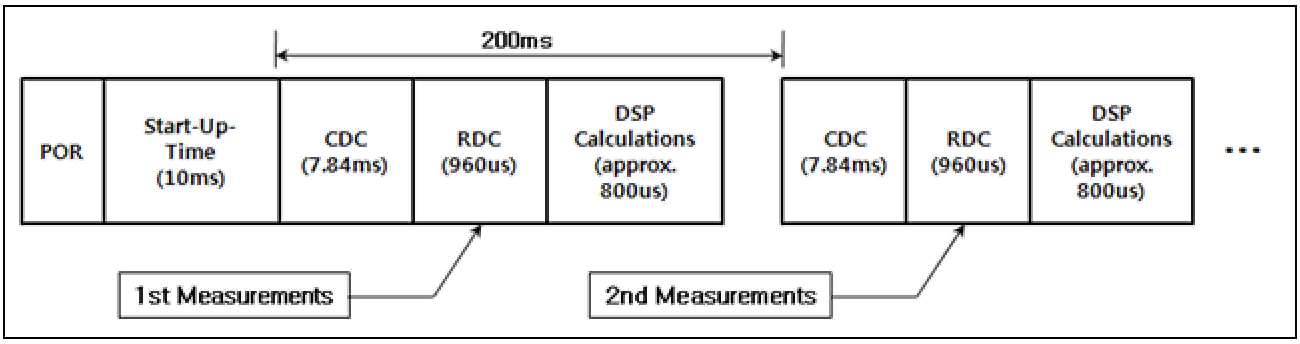
*1 : This value is the current consumption for the internal process to generate PDM. The current for an sink of PDM-output is not included.

4. Communicating with HumiChipII®

4.1 Power–On Sequence

On system Power-On-Reset, the **HumiChipII®** wakes as an I²C device. After power-on-reset, start-up-time is required 10ms.
The CDC is triggered by the conversion timer. After the CDC is completed, the RDC will be performed sequentially. Then the DSP calculate and update the humidity and temperature to Result Register. The measurement rate is 5㎐ (200㎳) by conversion timer. See the Figure 4 Power-on Sequence.

Figure 4 Power-On Sequence



4.2 I²C Compatible Interface

The present paragraph outlines the **HumiChipII®** device specific use of the I²C interface. The external master (**HumiChipII®** cannot be master) begins the communication by creating a start condition, falling edge on the SDA line while SCL is HIGH. It stops the communication by a stop condition, a rising edge on the SDA line while SCK is high. Data bits are transferred with the rising edge of SCK.

On I²C buses, every slave holds an individual 7-bit device address (0x28 fixed). This address has always to be sent as the first byte after the start condition. The eighth bit indicating the direction of the following data transfer (Read : 1 and Write : 0). The address byte is followed by the opcode and eventually the payload. Each byte is followed by an acknowledge bit (0 : when a slave acknowledges).

Figure 5 Address Byte

MSB							LSB
0	1	0	1	0	0	0	R/W

Figure 6 START and STOP condition

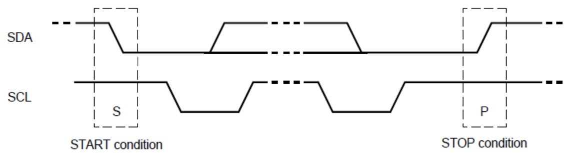
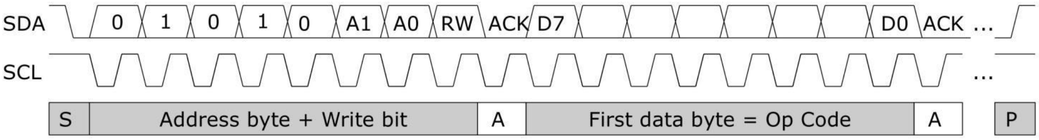


Figure 7 I²C principle sequence



4.2.1 I²C Write

During write transactions, the master alone sends data, the addressed slave just sends the acknowledge bit. The master first sends the slave address plus the write bit. Then it sends the HumiChipII® specific opcode including the register address in the slave. Finally it sends the payload ("Data").

Figure 8 I²C Write procedure

S	I2C-Address + W	A	Opcode + Write address	A	Write address	A	Data	A	P

4.2.2 I²C Read

During read transactions, the direction of communication has to be commuted. Therefore, the master creates again a start condition and sends the slave address plus the read bit (instead of the write bit) to switch into read mode.
Figure 8 shows.

Figure 9 I²C Read procedure

S	I2C-Address + W	A	Opcode + Read address	A	Read address	A	S	I2C-Address + R	A	Data	N	P

After arrival of the first (or any) data byte, the master may be either signal Not-Acknowledge or Acknowledge.
Not-Acknowledge (=N=1) indicate "end of read" and "stop sending" to the slave.
Acknowledge (=A=0) indicate "continue in automatic address-increment mode" and thus receive many bytes in a row. As one can see, automatic address increment is particularly useful and efficient with the I²C interface.

4.2.3 I²C Timing

The HumiChipII® uses I²C-compatible communication protocol with support for Max 100 ㎑ bit rates. See Figure 10 and Table 4.

Note : *Please refer to the I²C-bus specification for Detailed Timing Chart. And Reference Programming Code are available upon request.*

Figure 10 Definition of timing for device on the I²C-bus

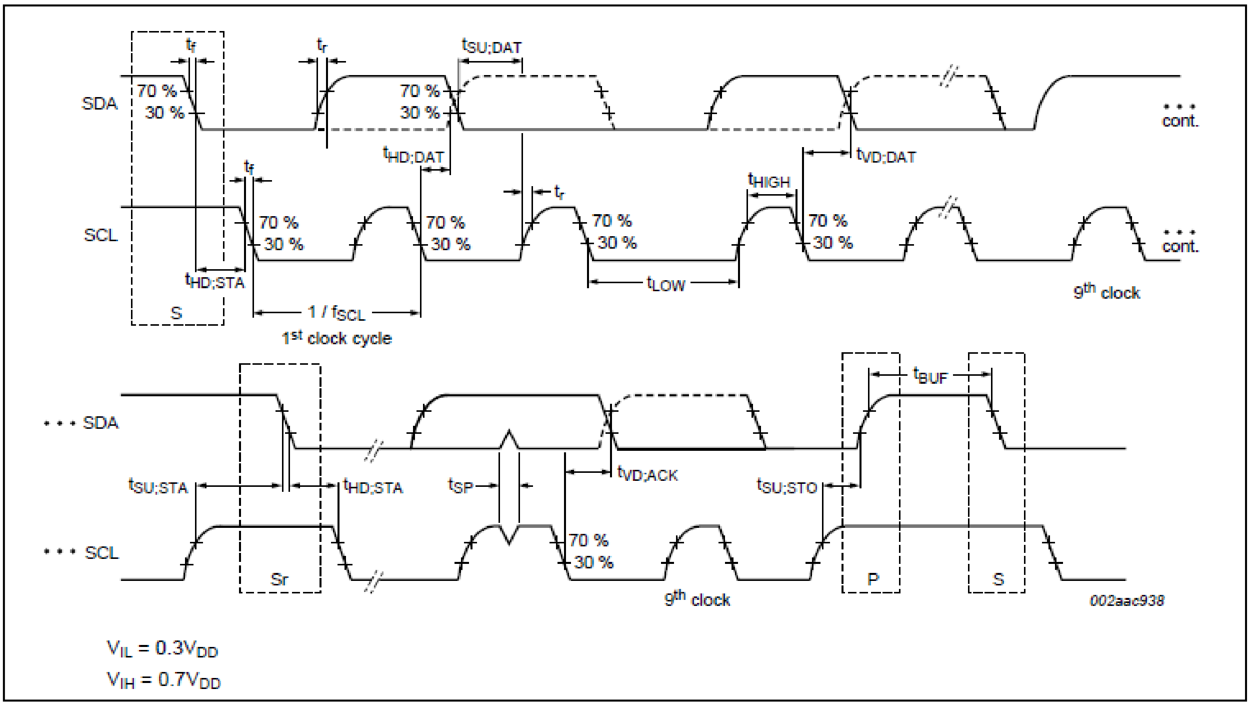


Table 4 Characteristics of the SDA and SCL bus lines

PARAMETER	SYMBOL	MIN	MAX	UNIT
SCL clock frequency*1	f_{SCL}	0	100	kHz
hold time (repeated) START condition	$t_{HD:STA}$	4.0		µs
LOW period of the SCL clock	t_{LOW}	4.7		
HIGH period of the SCL clock	t_{HIGH}	4.0		
set-up time for a repeated START condition	$t_{SU:STA}$	4.7		
data hold time*2	$t_{HD:DAT}$	0		
data set-up time	$t_{SU:DAT}$	250		ns
rise time of both SDA and SCL signals	t_r		1000	ns
Fall time of both SDA and SCL signals	t_f		300	ns
set-up time for STOP condition	$t_{SU:STO}$	4.0		µs
Bus free time between a STOP and START condition	t_{BUF}	4.7		µs
capacitive load for each bus line	C_b		400	pF
data valid time	$t_{VD:DAT}$		3.45	µs
data valid acknowledge time	$t_{VD:ACK}$		3.45	µs

1. Overclocking is technically possible but within the sole responsibility of the customer (a license may be necessary)
2. The data hold time that is measured from the falling edge of SCL, applies to data in transmission and the acknowledge. A device must internally provide a hold time of at least 300 ns for the SDA signal to bridge the undefined region of the falling edge of SCL.

4.3 Opcode

All commands for write or read to memory or configuration or result registers may use explicit addressing or address auto-increment.
Note : *Besides the case of reading the result registers, it is recommended to deactivate the converter for any communication to configuration registers or EEPROM. This is done by setting the RunBit to '0'. After the communication process the RunBIt needs to be set back to '1'.For more details, see the* ***Section 4.7.***

Table 5 Opcode

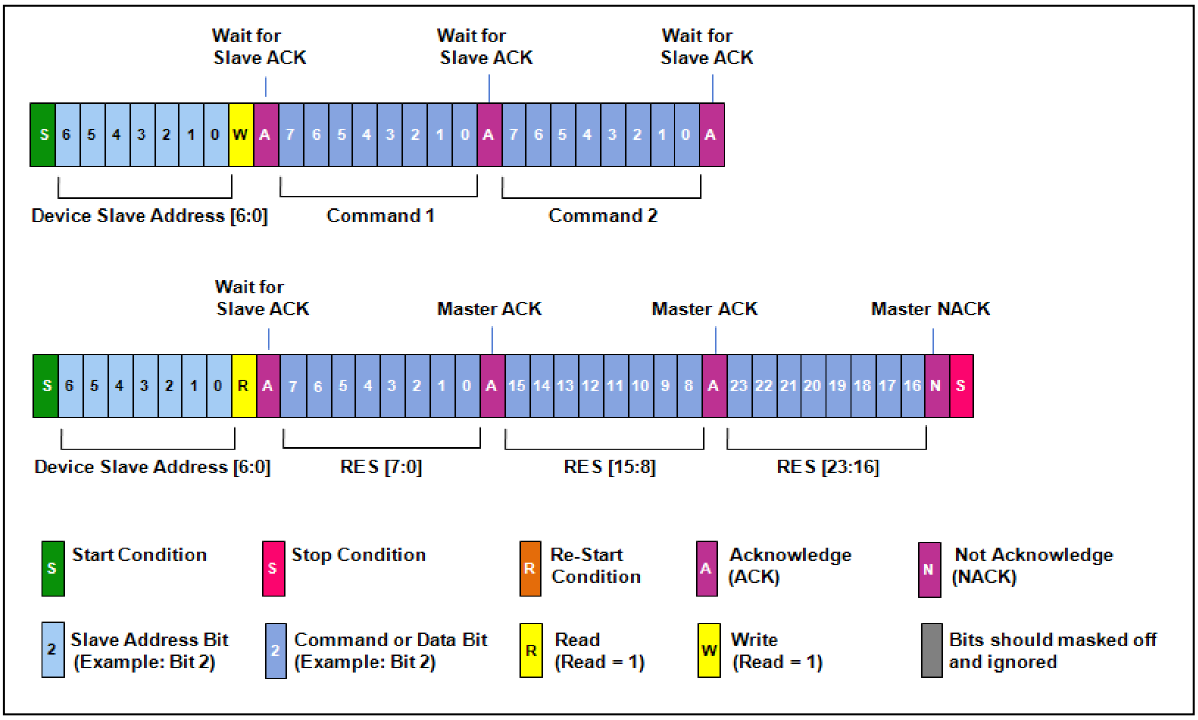
Description	BYTE 2								BYTE 1		BYTE 0
Read Result	0	1	0	0	0	0	0	0	0	Addr <6..0>	
Write configuration	1	1	0	0	0	0	0	0	0	Addr <6..0>	Data <7..0>
Write EEPROM	1	1	1	0	0	0	0	0	0	Addr <6..0>	Data <7..0>
Read EEPROM	0	1	1	0	0	0	0	0	0	Addr <6..0>	
Erase EEPROM	1	1	1	0	0	0	1	0	0	Addr <6..0>	[Dummy Byte]
Power-on Reset*1	1	0	0	0	1	0	0	0			

1. It takes about 280us until the first(cdc) measurement starts.

4.4 Data Fetch

The Data Fetch (DF) command is used to fetch data from **HumiChipII®**. An I^2C Data Fetch command starts with the 7-bit slave address and the 8^{th} bit 1(Read). The **HumiChipII®** as the slave sends an acknowledgement (ACK) indicating success.
The number of data bytes returned by the **HumiChipII®** is determined by when the master sends the NACK and stop condition. Figure 11 shows examples of fetching three bytes respectively.

Figure 11 I^2C Measurement Packet Reads



The data has to be read from Result Register (see Table 7) using the Read Result command in order to fetch the humidity and temperature. Read Result command consists of 0x40 and 7-bit address. 7-bit address is 0x00(for temperature) or 0x03(for humidity). After commands are transferred, 3-bytes data is read from HumiChipII®. First 2-bytes are humidity or temperature. They are signed integer, two's complement fixed- point. The lower byte is fractional digits and the higher byte is integer values. Third byte is Checksum. If it isn't used, only 2-bytes can be read.

The checksum and output data are calculated as Table 6.

To read temperature and humidity at a time, data of 6-Bytes can be fetched from HumiChipII® after commands(0x40+0x00) are sent. The first 3-bytes are temperature and the next 3-bytes are humidity.

Figure 12 Example : Temperature and Humidity data fetch

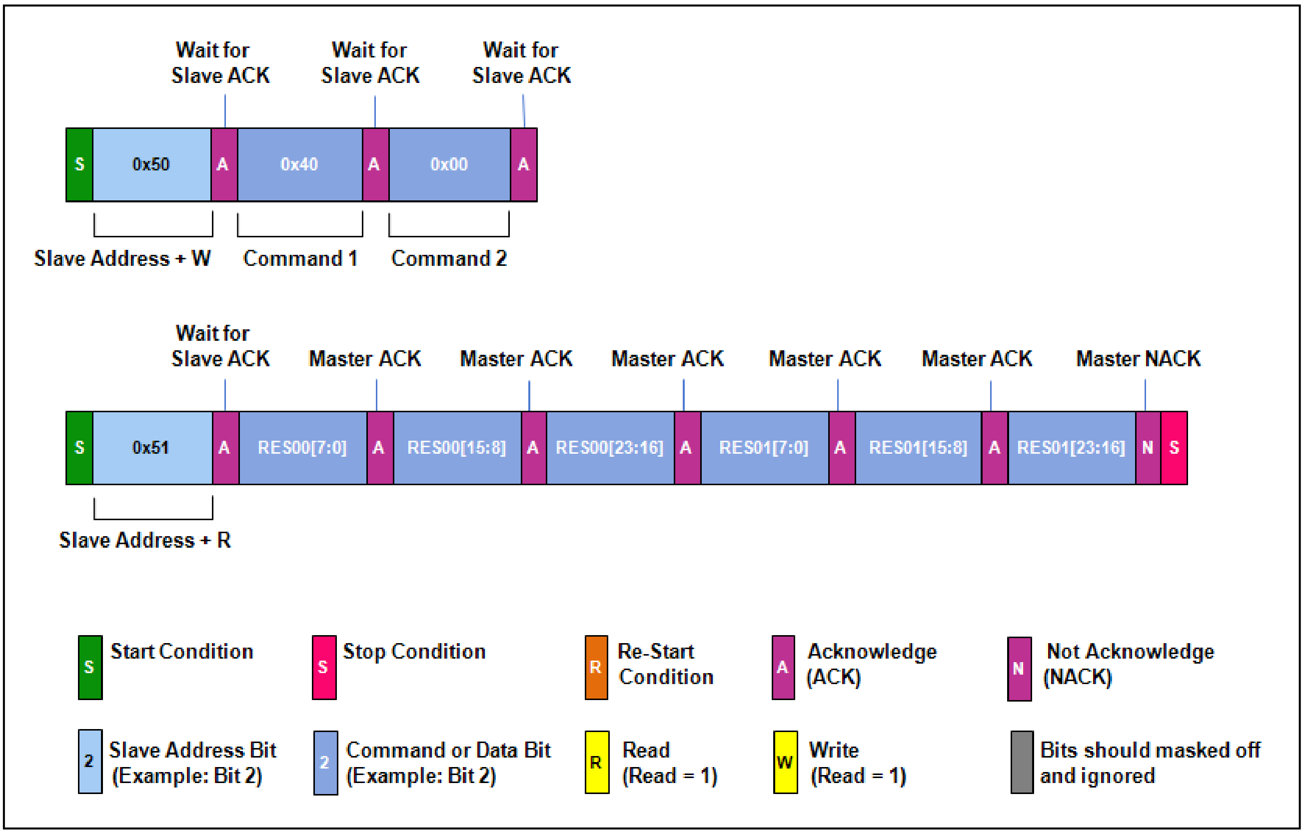


Table 6 Humidity & Temperature Conversion Formula

Humidity & Temperature Conversion Formula	
Humidity Output (%RH)	RES01[15:0] / 256
Temperature Output (°C)	RES00[15:0] / 256
Checksum	RES[23..16] = (RES[15..8] + RES[7:0]) % 256

Note : *'%' symbol in Checksum Formula means mod operation.*

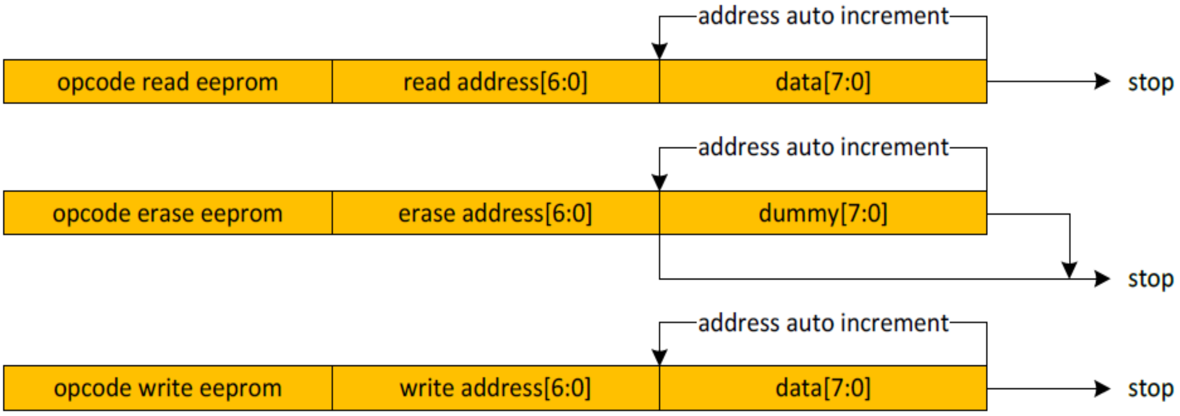
Table 7 Result Register

Name	Res	Address	fpp	Description
Temperature (℃)	00	0..2	8	Determined temperature in ℃ (-40 ~ 125℃)
Humidity (%RH)	01	3..5	8	Determined relative humidity in %RH (0 ~ 100%RH) (Temperature compensated)

4.5 EEPROM

The EEPROM array contains the calibration coefficients for gain and offset, etc., and the configuration bits for the output modes, measuring rate, etc.. The **HumiChipII**® EEPROM is arranged as 127 Bytes (see Table 11). See **Section 4.3** for instructions on reading and writing to the EEPROM via the I²C interface. When programming the EEPROM, an internal charge pump voltage is used; therefore a high voltage supply is not needed.
Only 1's can be written to the EEPROM. Therefore, it is necessary to erase the EEPROM cells before writing new data. EEPROM communication may use address auto-increment. In case of "Erase EEPROM" the incremental write is achieved by sending additional dummy bytes.

Figure 13 EEPROM communication



It is necessary to wake up the EEPROM before each write access. Therefore, Enable EEPROM after clear RunBit. The EEPROM wakeup can be done explicitly or automatically. It is mandatory to take care of the setup timings, for each individual byte.

Table 8 EEPROM Timings

Symbol	Description	Typ.
t_{rdsu}	Set-up Time for reading	300㎲
t_{rd}	Read Time from EEPROM	600㎱
t_{wrsu}	Set-up Time for Writing	200㎲
t_{wr}	Write Time to EEPROM	6.8㎳

4.6 Configurations

4.6.1 RunBit

The RunBit enables or disables the front-end and the DSP. It is indicated in the Status Register bit0. When the Configuration Register or EEPROM is accessed, the Runbit should be '0'. Then, as a last step, RunBit should be set to '1' again.
Use the POR command in order to re-start the measurement after access is completed.

Table 9 Commands for configurations

Command	CMD1	CMD2	CMD3
Set RunBit	0xC0	0x4D	0x01
Clear RunBit	0xC0	0x4D	0x00
Enable EEPROM	0xC0	0x1C	0xC4
Disable EEPROM	0xC0	0x1C	0x44

4.6.2 Status Register

Address 24 in the Result Register is the Status Register. The EEPROM state and the RunBit are displayed in the Status Register.

For more information, see **Section 4.6 EEPROM** and **Section 4.7.1 RunBit**.

Table 10 Status Register Details

Bit#	Name	Description
0	RunBit	Run Bit (0: Disable, 1: Enable)
2:1	Reserved	
3	EE_BUSY	EEPROM busy
7:4	Reserved	

Figure 14　EEPROM power controlled by user : Write / Erase

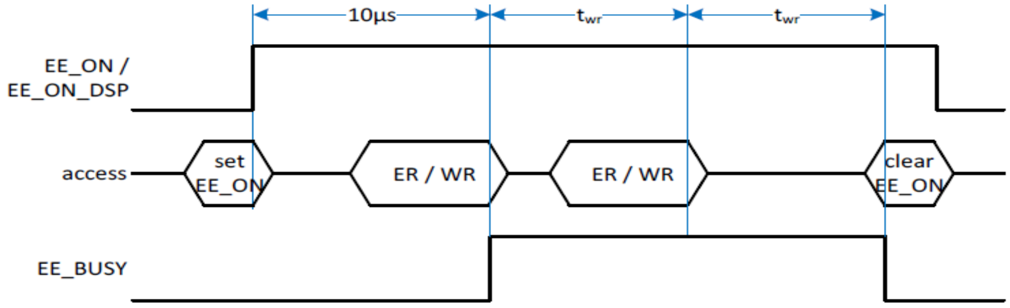


Figure 15　EEPROM power controlled by user : Read

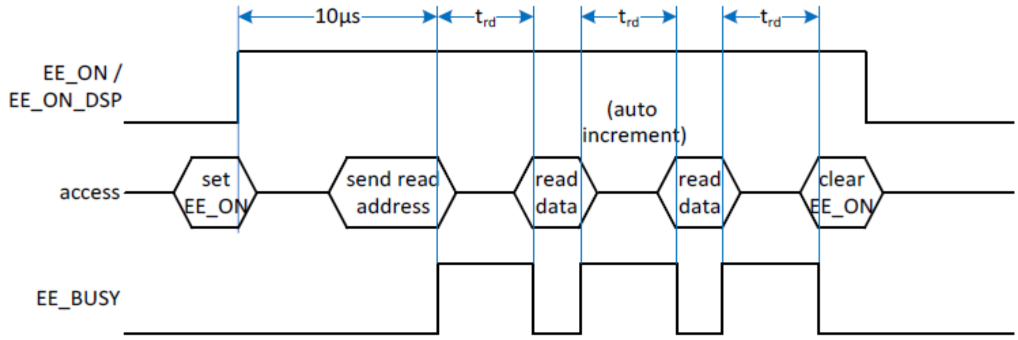


Figure 16　EEPROM power controlled automatically : Write / Erase

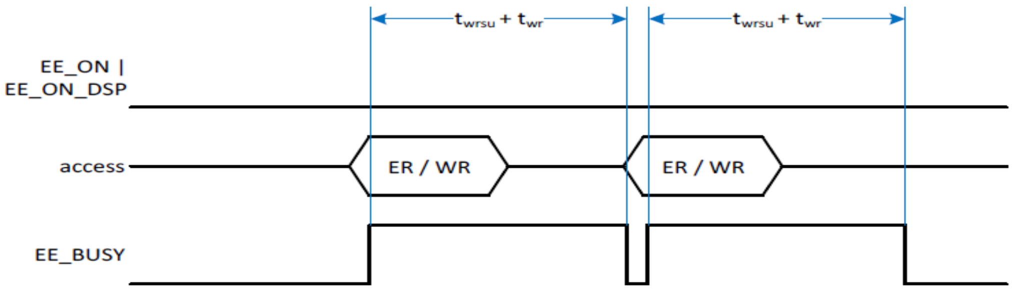


Figure 17　EEPROM power controlled automatically : Read

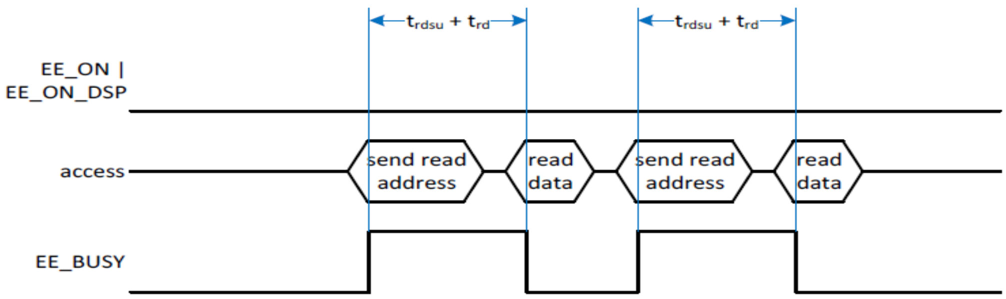


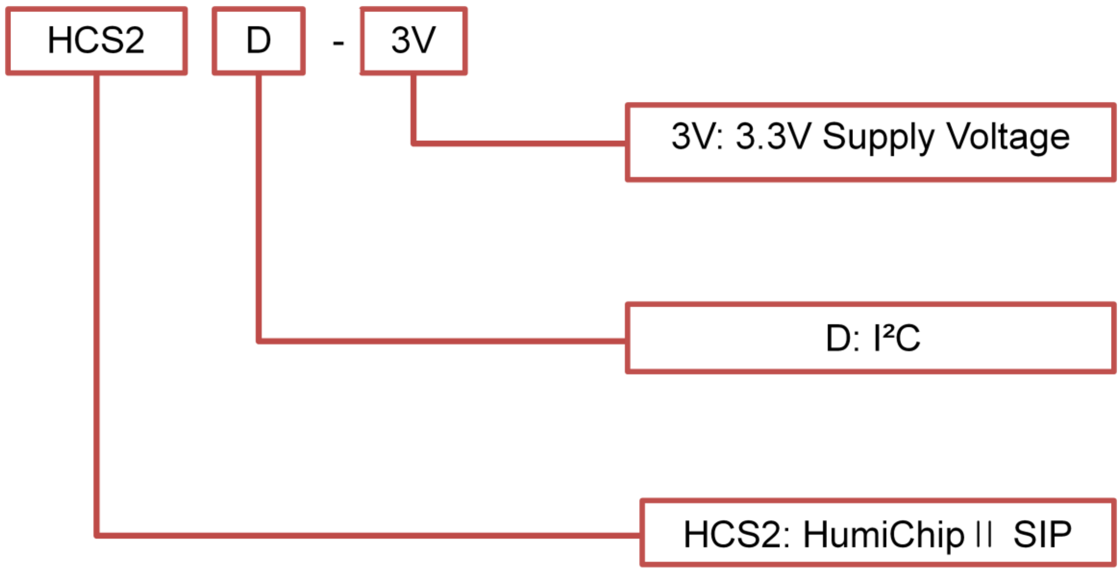
Table 11 EEPROM Assignments

Address (HEX)	Bit Range	Default	Name	Description and Notes
84(54h)	15:8	0x00	Alarm_High_On	High alarm on trip point (16bits signed integer, two's complement, fixed point with 8fpp)
85(55h)	7:0	0x00		
86(56h)	15:8	0x00	Alarm_High_Off	High alarm off trip point (16bits signed integer, two's complement, fixed point with 8fpp)
87(57h)	7:0	0x00		
88(58h)	15:8	0x00	Alarm_Low_Off	Low alarm off trip point (16bits signed integer, two's complement, fixed point with 8fpp)
89(59h)	7:0	0x00		
90(5Ah)	15:8	0x00	Alarm_Low_On	Low alarm on trip point (16bits signed integer, two's complement, fixed point with 8fpp)
91(5Bh)	7:0	0x00		
92(5Ch)	15:8	0x00	Pulse_Humi_ymin	Lower limit of voltage for PDM_H (16bits unsigned integer, two's complement)
93(5Dh)	7:0	0x00		
94(5Eh)	15:8	0x3F	Pulse_Humi_ymax	Upper limit of voltage for PDM_H (16bits unsigned integer, two's complement)
95(5Fh)	7:0	0xFF		
96(60h)	15:8	0x00	Pulse_Humi_xmin	Lower limit of humidity for PDM_H (16bits unsigned integer, two's complement, fixed point with 8fpp)
97(61h)	7:0	0x00		
98(62h)	15:8	0x64	Pulse_Humi_xmax	Upper limit of humidity for PDM_H (16bits unsigned integer, two's complement, fixed point with 8fpp)
99(63h)	7:0	0x00		
100(64h)	15:8	0x00	Pulse_Temp_ymin	Lower limit of voltage for PDM_T (16bits unsigned integer, two's complement)
101(65h)	7:0	0x00		
102(66h)	15:8	0x3F	Pulse_Temp_ymax	Upper limit of voltage for PDM_T (16bits unsigned integer, two's complement)
103(67h)	7:0	0xFF		
104(68h)	15:8	0xD8	Pulse_Temp_xmin	Lower limit of temperature for PDM_T (16bits signed integer, two's complement, fixed point with 8fpp)
105(69h)	7:0	0x00		
106(6Ah)	15:8	0x7D	Pulse_Temp_xmax	Upper limit of temperature for PDM_T (16bits signed integer, two's complement, fixed point with 8fpp)
107(6Bh)	7:0	0x00		
127(7Fh)	7:0	0x09	Config Byte	

Table 12 EEPROM Config Byte

Bit	Name	Default	Description
0	Digital_EN	1	**Switch on PDM outputs** 0: PDM Temperature and Humidity are enabled 1: Alarm Low and Ready are enabled
2:1	Reserved	00	**Do not change** – must leave at factory settings
3	Checksum_EN	1	**Output data with checksum** 0: Original data 24 bit signed (8 fractional bits) 1: Output data with checksum 16 bit signed (8 fractional bits + 8 integer bits) + 8 checksum bits
4	Measure Rate Slow	0	0 : 5㎐ Measure Rate 1 : 1㎐ Measure Rate
5	LowPassFilter_EN	1	0 : Low Pass Filter off 1 : Low Pass Filter Active
7:6	Reserved	00	**Do not change** – must leave at factory settings

HumiChipII® Part Number



Items	Series	Output	Operating Voltage(V)	mode	Accuracy(%RH)	Part Number
Humi D	HCS (SIP)	I^2C (Digital)	3.3V	Update	±2%RH	HCS2D-3V

5. Revision History

Date	Version	Page(s)	Changes
9 JULY 2015	1.0		

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